

Product Change Notification - KSRA-19VAHD748 [\(Printer Friendly\)](#)

Date:

27 Apr 2017

Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers; 8-bit PIC Microcontrollers

Notification subject:

CCB 2924 and 2924.001 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technology available in 28L QFN-S package at NSEB assembly site

Notification text:
PCN Status:

Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technology available in 28L QFN-S package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T and 8600 die attach and G770HCD and G700LTD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

| | Pre Change | | Post Change |
|----------------------------|--------------------|------|--------------------|
| Assembly Site | NSEB Assembly Site | | NSEB Assembly Site |
| Wire material | Au Wire | | CuPdAu Wire |
| Die attach material | 8200T | 8600 | 8600 |

| | | | |
|----------------------------------|---------|---------|---------|
| Molding compound material | G770HCD | G700LTD | G700LTD |
| Lead frame material | C194 | | C194 |

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

October 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

| Workweek | April 2017 | | | | | | → | October 2017 | | | | |
|--------------------------|------------|----|----|----|----|----|---|--------------|----|----|----|----|
| | 13 | 14 | 15 | 16 | 17 | 18 | | 40 | 41 | 42 | 43 | 44 |
| Initial PCN Issue Date | | | | | X | | | | | | | |
| Qual Report Availability | | | | | | | | X | | | | |
| Final PCN Issue Date | | | | | | | | X | | | | |

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

April 27, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-19VAHD748_Affected CPN.pdf](#)

[PCN_KSRA-19VAHD748_Qual Plan.pdf](#)

[PCN_KSRA-19VAHD748_Affected CPN.xlsx](#)

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